

TE 362

LECTURE 2:

Passive Devices

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Impedance Characteristics

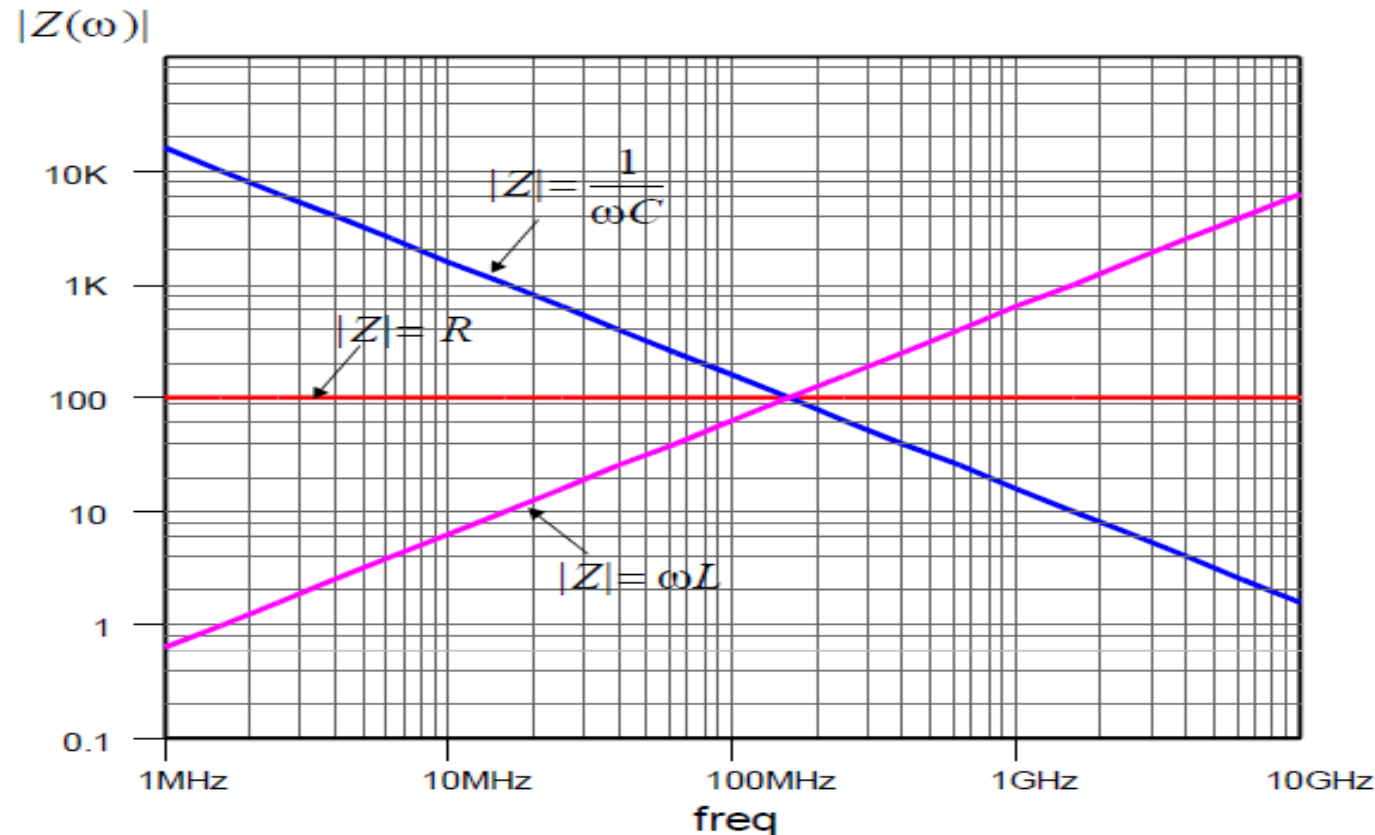
- ❑ Passive devices include resistors, capacitors, and inductors.
- ❑ When these are used in a circuit, the most fundamental consideration is their impedance.
- ❑ The impedance of resistor, capacitor and inductor, are respectively expressed as below:

$$Z_R = R$$

$$Z_C = \frac{1}{j\omega C}$$

$$Z_L = j\omega L$$

Plot of the Magnitude of the Impedances on a Log-Log Scale



□ Impedances of resistor, capacitor and inductor

Impedance Characteristics vs Frequency



- ❑ Commercially available resistors, capacitors and inductors, may have non-ideal characteristics.
 - ❖ the impedance characteristic generally becomes more complicated as frequency increases, and
 - ❖ it becomes necessary to examine their characteristics in advance during circuit design.

Impedance Characteristics vs Frequency



□ At low frequencies,

- ❖ The passive devices exhibit the ideal impedance characteristics;
- ❖ however, a very complicated equivalent circuit is needed in practice for their representation as the frequency increases,
- ❖ adding to the difficulty and complexity of the circuit design.

Impedance Characteristics vs Frequency

□ In such circumstances,

❖ the equivalent circuit that properly reflects these characteristics in the frequency band of operation should be used in the circuit design.

□ Understanding of

❖ typical equivalent circuit of such commercially available passive devices, and

❖ the technique to determine the equivalent circuit values with a given data is basic.

Impedance Characteristics vs Frequency



- ❑ Typical forms of data are available as datasheets and library in design software.
- ❑ When data are not available,
 - ❖ measurements or
 - ❖ EM simulations can be done to determine the equivalent circuits.

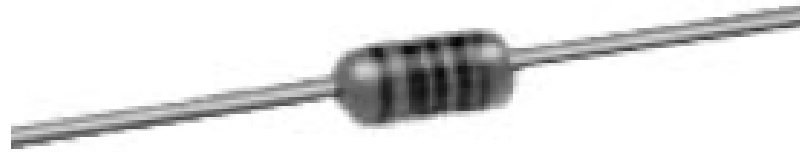
Classification of Passive Devices

□ Passive devices

- ❖ are largely classified based on the fabrication method, and are divided into:
- ❖ *lead components,*
- ❖ *chip-type components,* and
- ❖ *passive components formed by patterns.*

□ Lead-type and Chip-type components are widely available commercially

Lead-type Passive Devices



(a)



(b)



Type A



Type X



Type M



Type P

(c)

(a) resistor

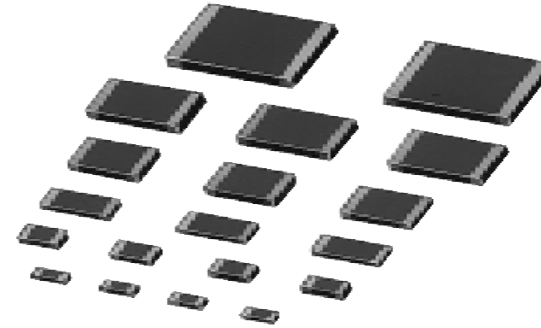
(b) capacitor

(c) inductor

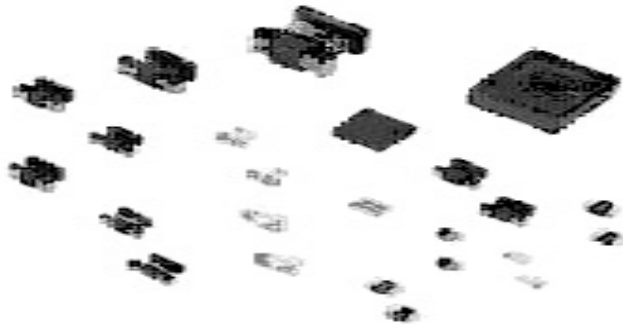
Chip-type Passive Devices



(a)



(b)



(c)

(a) resistor

(b) capacitor

(c) inductor

Assembly of Lead-type Component

- Lead-type components are assembled by insertion
 - ❖ The lead terminals are first bent and inserted into through-holes made in the printed circuit board.
 - ❖ The lead terminals are then cut, and
 - ❖ the printed circuit board with lead type components is dipped into melt solder.
 - ❖ Finally, the lead terminals are soldered to the round conductor patterns formed around the through-holes.

Lead-type Component

- ❑ Lead terminals of lead-type components
 - ❖ do not only serve the purpose of connection.
 - ❖ They also give rise to parasitic inductance for example at high frequencies, and
 - ❖ consequently this adds to the impedance of the passive device.
- ❑ These lead-type components were mostly used before chip-type components became commercially popular.
- ❑ Generally, they are bigger than chip-type components

Assembly of Chip-type Components

- ❑ Chip-type components are assembled by surface mounting technique (SMT).
- ❑ Solder creams are first printed to land-patterns formed on a printed circuit board or substrate, and
- ❑ chip-type components are mounted on the land patterns manually or automatically.
- ❑ Finally soldering to the land-patterns is completed by
 - ❖ assing through reflow machine with appropriate temperature profile

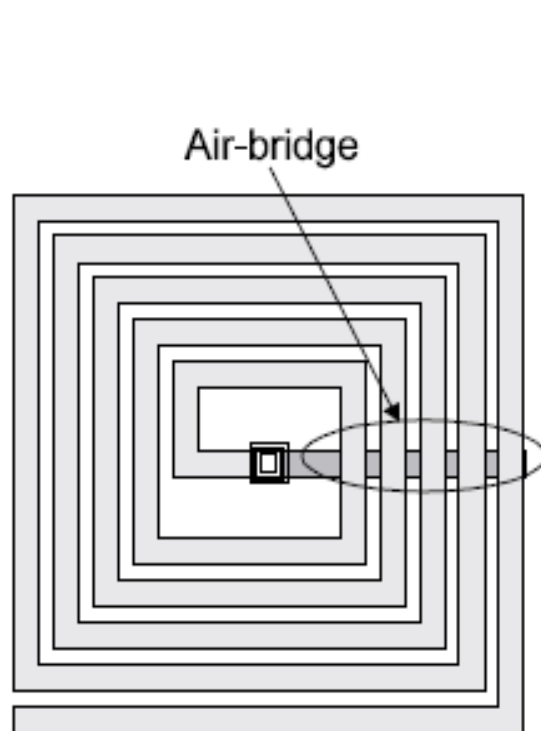
Chip-type Components

- ❑ Chip-type components compared to lead-type components
 - ❖ have relatively less parasitic elements caused by the terminals,
 - ❖ which becomes profitable at high frequency.
- ❑ The key reason for the popularity of these devices is
 - ❖ *miniaturization*
 - ❖ *surface-mounting feature*
 - ❖ rather than their advantage for use at high frequency.
 - ❖ SMT provides an advantage in large-scale fabrication.

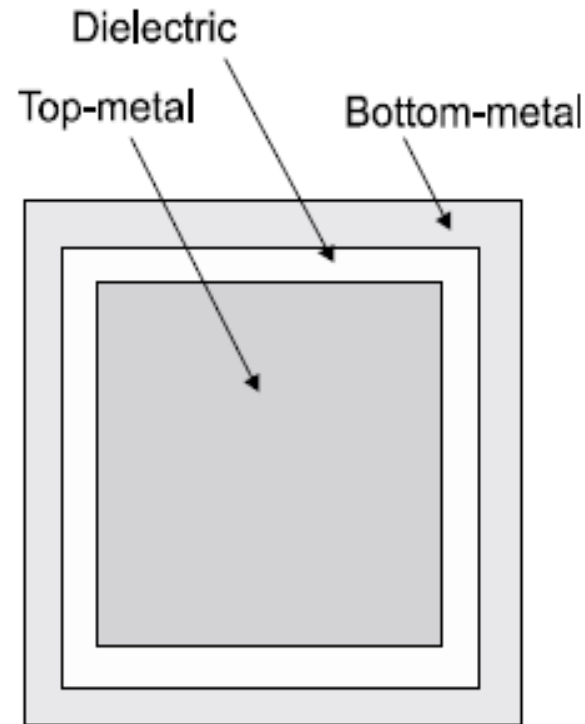
Pattern-formed Passive Components

- Pattern-formed passive components:
 - ❖ can be produced on the substrate
 - ❖ usually by the process of Monolithic Microwave Integrated Circuit (MMIC) or
 - ❖ thin film.
- passive devices by pattern formation
 - ❖ Are limited in the range of values attainable compared to chip-type or lead type devices,
 - ❖ which is a disadvantage.

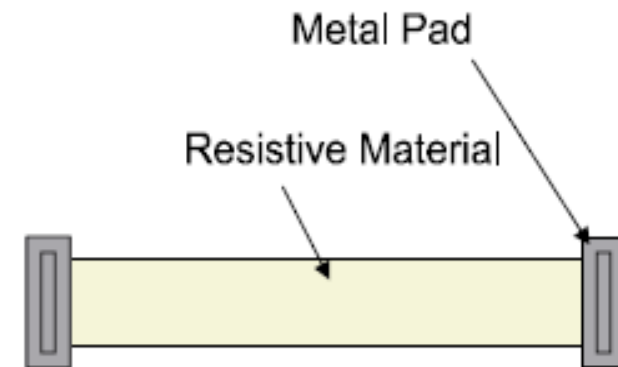
Pattern-formed Passive Components



(a) inductor



(b) capacitor



(c) resistor

Pattern Formed Resistor Components

□ Resistors

- ❖ A thin film of a resistive material (usually NiCr and TaN) forms the pattern, on which
- ❖ the conductor pattern (for the purpose of connection) is produced by proper technique.

□ The resistor has a uniform thickness

Pattern Formed Resistor Components

- The resistance is thus
 - ❖ proportional to the length L and
 - ❖ inversely proportional to the width (W).
 - ❖ The proportionality constant is defined as the *sheet resistivity* R_s , and the resistance R is given by:

$$R = R_s \frac{L}{W} ; R_s \text{ has the dimension of ohms/square}$$

Pattern Formed Capacitor Components

□ Capacitor

- ❖ A uniform thickness dielectric sheet is formed on the bottom conductor pattern.
- ❖ A top conductor pattern is again formed on the dielectric, and
- ❖ a Metal-Insulator-Metal (MIM) capacitor is formed.

□ At this point the dielectric material's thickness,

- ❖ generally determined by the process, and
- ❖ is constant

Pattern Formed Capacitor Components

- once the *sheet capacitance* C_s has been determined,
- the capacitance is then directly proportional to the surface area (A) and is expressed as:

$$C = C_s A$$

Pattern Formed Inductor Components

□ Inductor

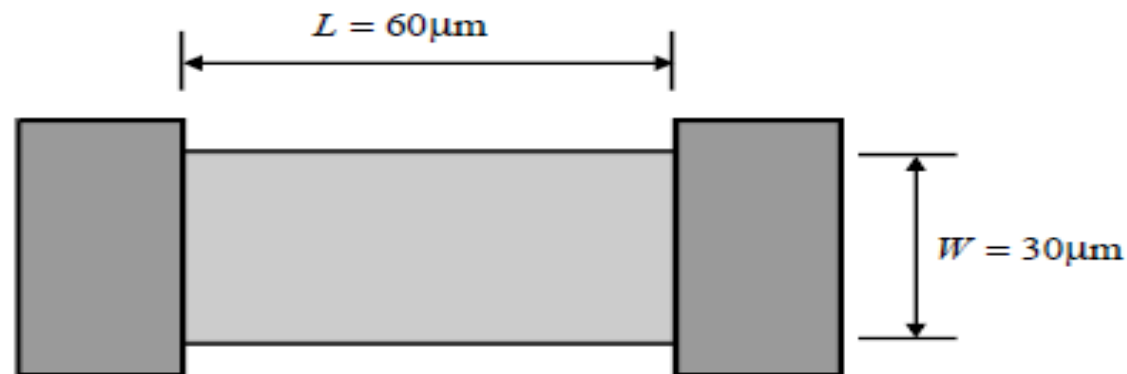
- ❖ Its design is not as simple as that of capacitor or resistor.
- ❖ Foundry service companies usually provide measurement results or data on several configurations of inductors; and
- ❖ in the absence of those, the values of inductors are determined through Electro-Magnetic (EM) simulation.

Pattern Formed Inductor Components

- When viewed from design point of view,
 - ❖ the construction of their equivalent circuit is the same as that of chip-type or lead-type components.
- NOTE: The parasitic characteristics increase with frequency

Example 1

- Given that the sheet resistance R_s is 50 ohm/square meter, calculate the resistance of the component shown below.
- In addition, the permittivity of a capacitor is 7.2 and its thickness is $0.4 \mu\text{m}$; determine the sheet capacitance in pF/mm and hence calculate the capacitance of a $50 \mu\text{m}^2$ capacitor.



Solution 1

$$R = R_s \frac{L}{W} = 50 \times \frac{60}{30} = 100 \Omega$$

□ For the capacitor, the sheet capacitance per square mm is;

$$C_s = \epsilon_r \epsilon_0 \frac{A}{t} = 8.854 \text{ pF/m} \times 7.2 \times \frac{1 \text{ m}^2}{0.4 \text{ m}}$$
$$= 8.854 \text{ pF/m} \times 7.2 \times \frac{1 \text{ m}}{0.4} \approx 159 \text{ pF}$$

□ Thus, $C_s = 159 \text{ pF/mm}^2$ and for a capacitor having an area of $50 \mu\text{m} \times 50 \mu\text{m}$ is; $C = C_s \times 0.05^2 = 159 \times 0.05^2 \text{ pF} = 0.398 \text{ pF}$

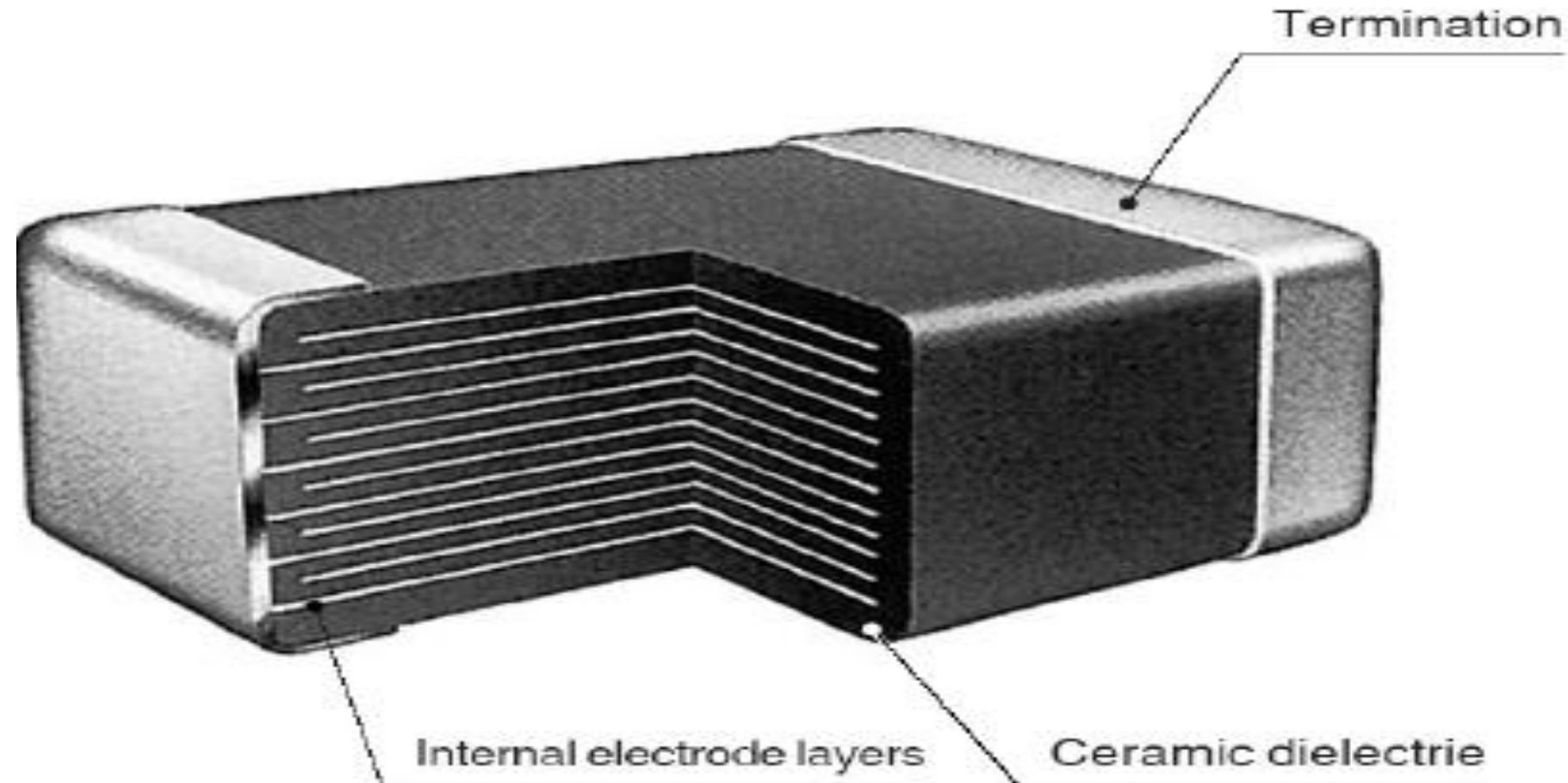
Equivalent Circuit of Chip-type Passive Devices

- ❑ In cases where thin film or MMIC process is not used,
 - ❖ the most likely choice for high frequency application is chip-type components and thus
 - ❖ they are widely used.
- ❑ chip-type device manufacturing and evaluation method will be discussed.
- ❑ In addition, the method of extracting the equivalent circuit from given data will be explained

Chip-type capacitor

- ❑ The chip capacitor is usually constructed in a multi-layer structure.
- ❑ The two soldered terminals are connected in parallel to a number of conducting plates, named as internal electrodes.
- ❑ The sum of the capacitance formed between the conducting plates appears at the terminals of the capacitor.
- ❑ The dielectric constant of the insulator filling the space between the conducting plates further increases the capacitance between the terminals.

Structure of a Chip Capacitor



Dimensioning of Chip-type Component

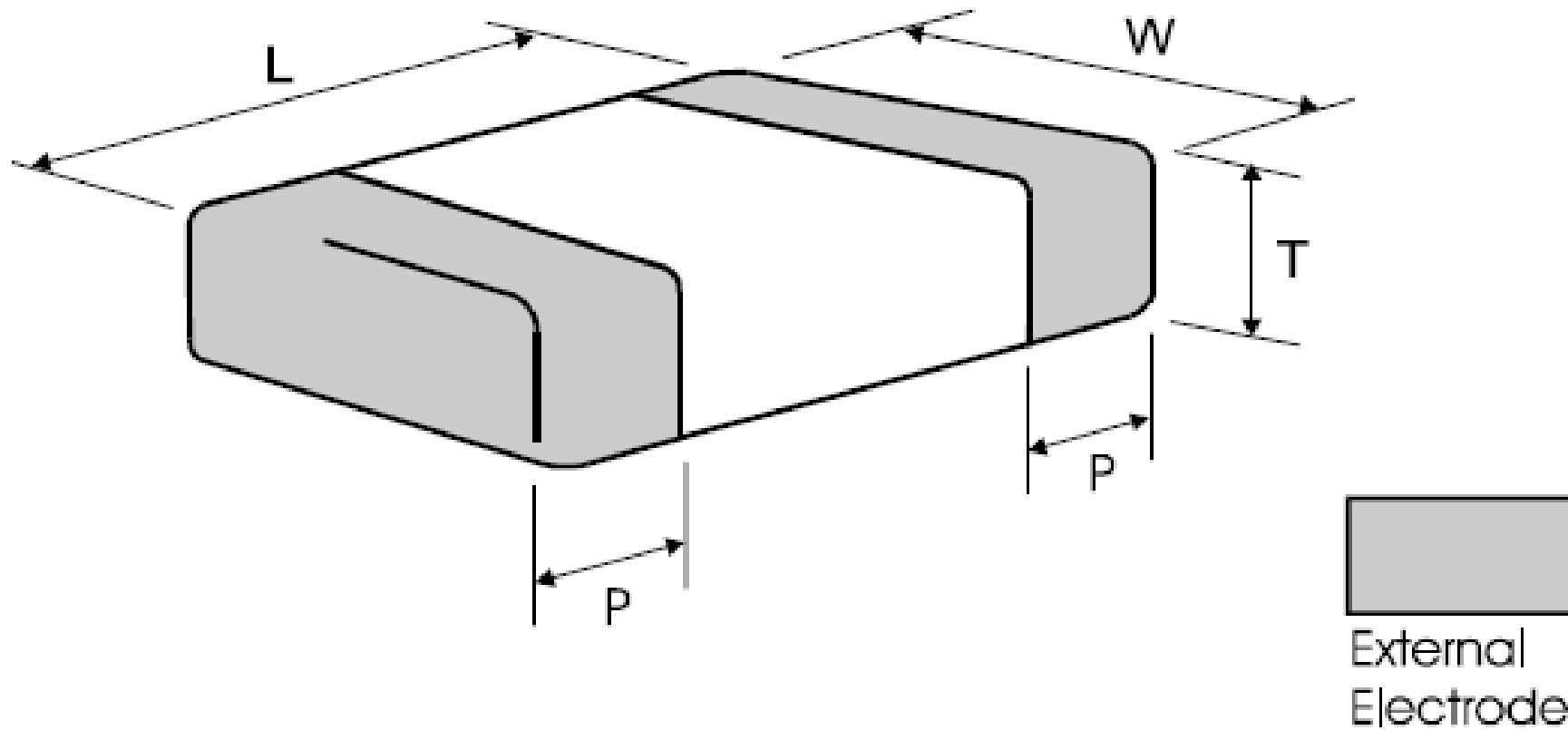


- They are identified based on two parameters;
 - ❖ length L between the terminals and
 - ❖ the terminal width, W .
- Based on a standard unit of mm;
 - ❖ a capacitor having a length of 1.0 mm and a width of 0.5 mm,
 - ❖ is called type 1005; and following a similar definition,
 - ❖ type 1608 is a capacitor which has a length of 1.6 mm and a width of 0.8 mm.

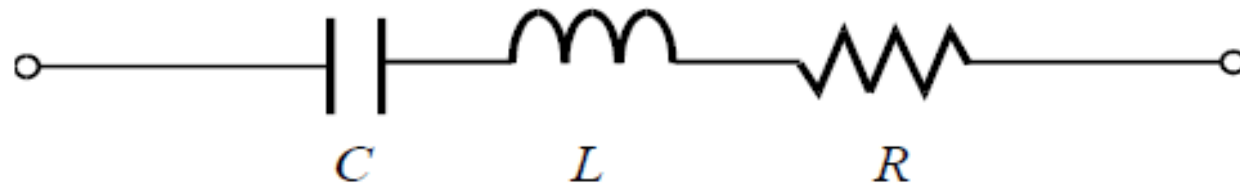
Dimensioning of Chip-type Component

- ❑ This classification applies to capacitors, resistors and inductors;
- ❑ for example,
 - ❖ a 1608 resistor similarly represents a chip resistor with a dimension of 1.6 mm length and 0.8 mm width.

Dimensions of a Chip-type Component



Equivalent Circuit of a Chip Capacitor



C : capacitance of the capacitor

L : parasitic inductance (0.7 nH ~ 1 nH)

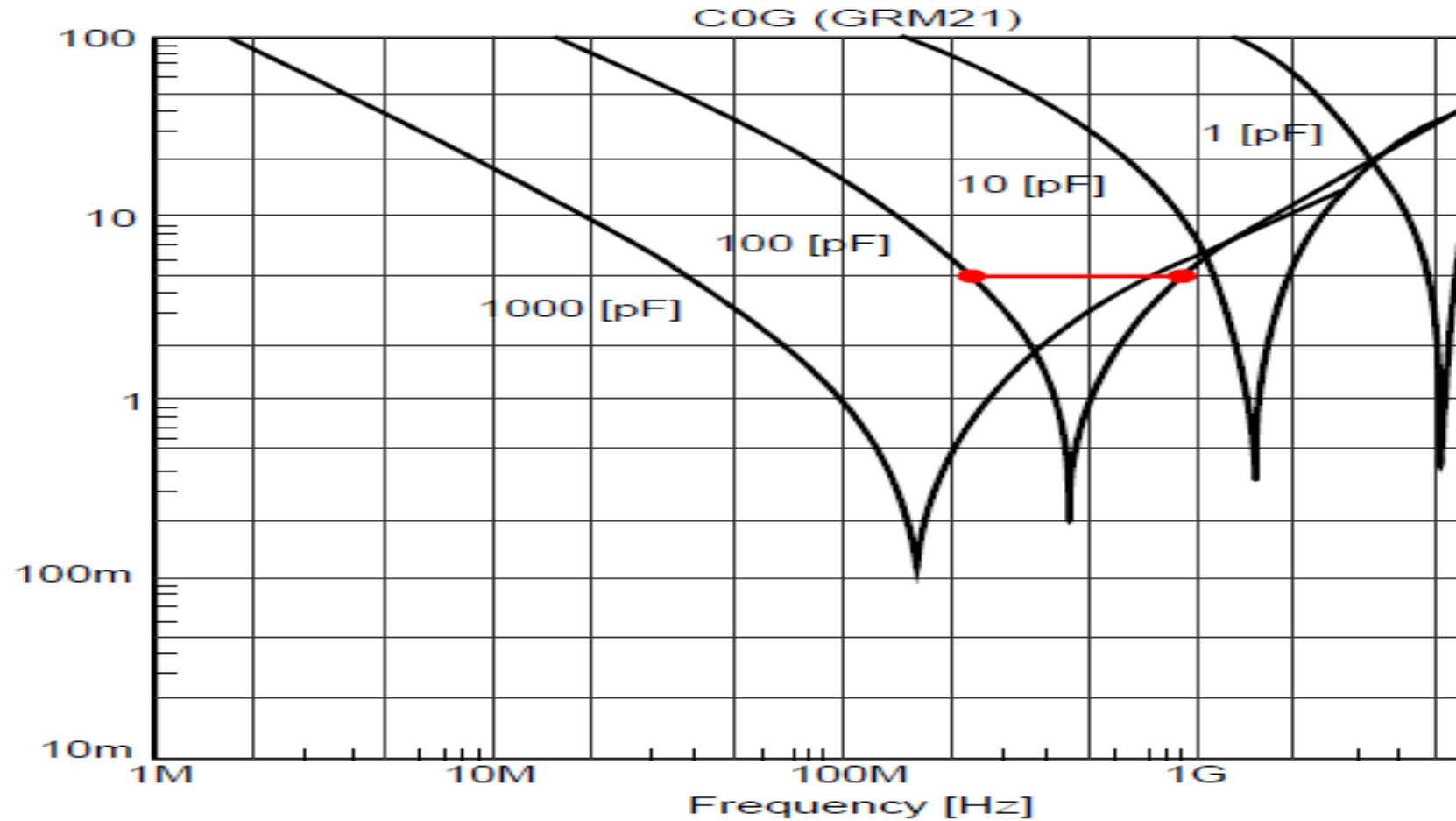
R : represents the loss of conductor plate

□ From the structural point of view,

❖ as the size of the capacitor becomes smaller, generally the inductance also becomes smaller, and

❖ With further reduction, the inductance generally tends to be constant regardless of the value of the capacitance.

Impedance Characteristics with Frequency



Impedance Characteristics with Frequency

- Looking at the 100 pF curve,
 - ❖ below a 100 MHz frequency, it can be seen that the impedance decreases linearly with frequency.
 - ❖ This is so because at low frequency, it behaves as a capacitor; and
 - ❖ since at 70 MHz, it shows about an impedance of 20 ohms,
 - ❖ it can be seen to have a capacitance value of:

$$C = \frac{1}{2\pi fX_C} \cong \frac{1}{2\pi \times 70 \times 10^6 \times 20} = \frac{1000}{2\pi \times 1.4} \text{ pF} \cong 113 \text{ pF}$$

Impedance Characteristics with Frequency

- ❑ The error in the calculated capacitance if any
 - ❖ will be due to the approximation in the reading of the impedance value from the graph.
- ❑ As the frequency increases,
 - ❖ the impedance after reaching a minimum rises again.
- ❑ While the impedance of the capacitor
 - ❖ is decreasing,
 - ❖ that of the inductor is increasing with frequency,

Impedance Characteristics with Frequency

- thus, as the frequency becomes much higher,
 - ❖ the capacitor behaves as an inductor,
 - ❖ which explains why the impedance increases with frequency.
- Considering the minimum point of the 100 pF curve,
 - ❖ the resistor in the equivalent circuit is found to have a series resistance value of approximately $R = 0.2$ ohm.

Impedance Characteristics with Frequency

- Although the value of the inductor
 - ❖ is inaccurate only with this data,
 - ❖ assuming that at a frequency of 1 GHz the impedance is mainly by an inductor;
 - ❖ then since its impedance is approximately 6 ohm at this frequency;
 - ❖ its value is found to be:

$$L = \frac{X_L}{2\pi f} \cong \frac{6}{2\pi \times 1 \times 10^9} = \frac{6}{2\pi} \text{ nH} \cong 1 \text{ nH}$$

Impedance Characteristics with Frequency

- ❑ This shows that, data at higher frequency will be needed in order to determine this value more accurately.
- ❑ Thus, in the case of the 100 pF capacitor,
 - ❖ when used at a frequency of over 1 GHz
 - ❖ it is closer to being an inductor rather than a capacitor.
- ❑ If used as a DC block,
 - ❖ it must have an impedance of about 5 ohm
 - ❖ which is estimated as 1/10 of a standard impedance; considering standard impedance is 50 ohm).

Impedance Characteristics with Frequency

- It is possible to use this capacitor
 - ❖ as a DC block or a bypass capacitor between the frequencies of 300 MHz to 900 MHz;
 - ❖ but due to the effect of the inductor, its use as DC block at a higher frequency poses a difficulty.

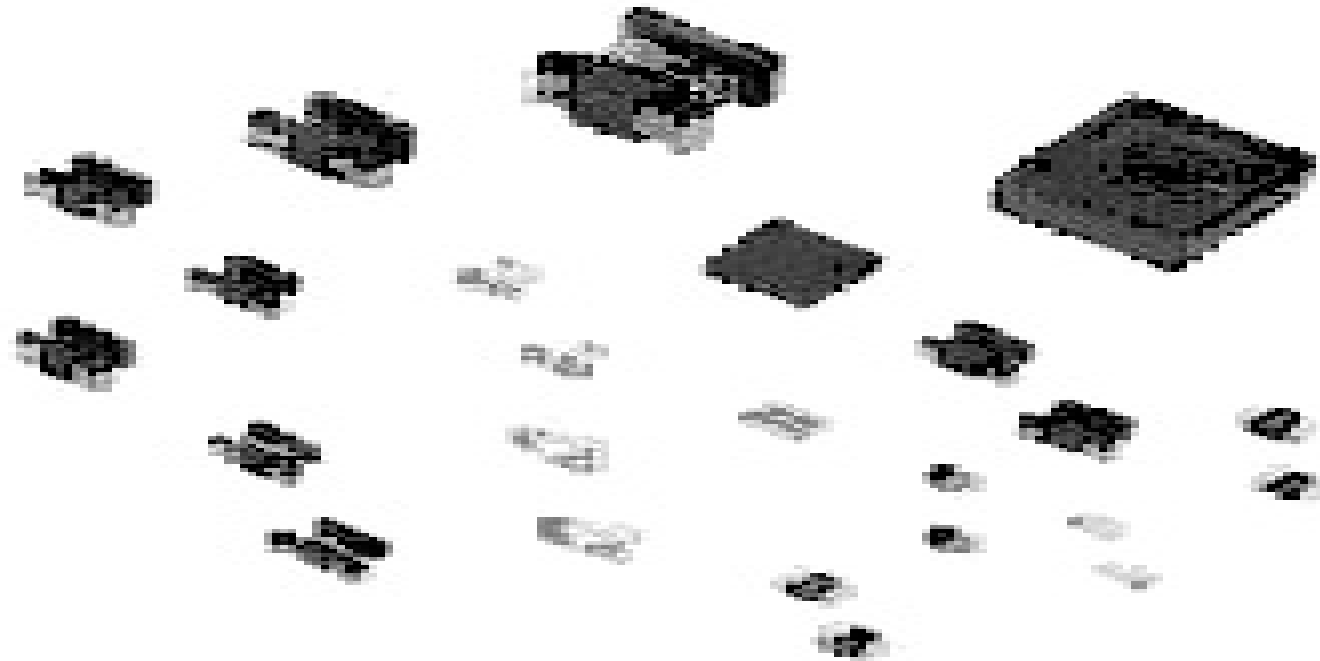
Chip-Type Inductors

- To obtain the inductance,
 - ❖ an enamel coated copper wire is wound on a core of ferrite material between the terminals to be soldered.
 - ❖ More winding is possible as the diameter of such wire is made a lot thinner,
 - ❖ which results in higher inductance.
- It should however be noted that,
 - ❖ this will lead to increasing series resistance and
 - ❖ decreasing current capacity on the other hand.

Chip Inductors (Murata chip inductors)

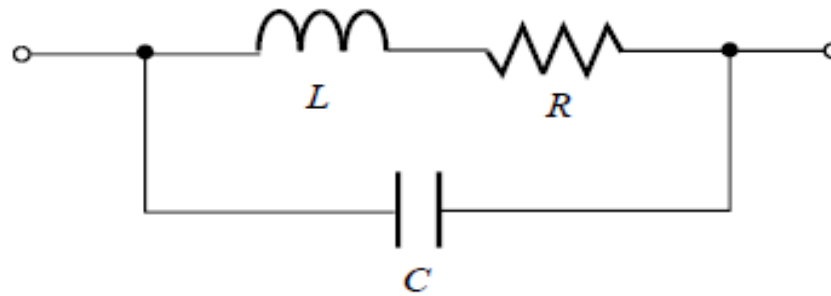
- The inductance can be significantly increased by
 - ❖ increasing the number of windings;
 - ❖ but this will also lead to a proportional increase of parasitic capacitance.
- Therefore,
 - ❖ as the inductance becomes larger,
 - ❖ they are usually not be used at high frequency and when designing a circuit,
 - ❖ there will be the need to use given data to verify the frequency range of operation

Chip Inductors (Murata chip inductors)

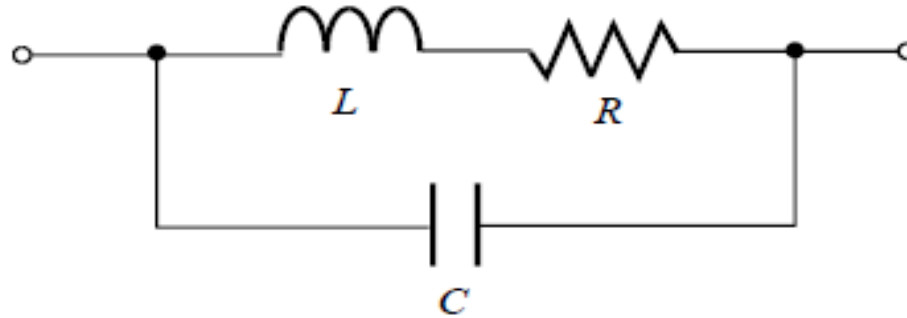


Equivalent circuit of an inductor

- The figure below is a typical electrical equivalent circuit of an inductor;
- ❖ where L represents the inductance arising from the winding and
 - ❖ R represents the winding resistance.
 - ❖ The C in the equivalent circuit also represents the parasitic capacitance appearing between the windings.



Equivalent circuit of an inductor...



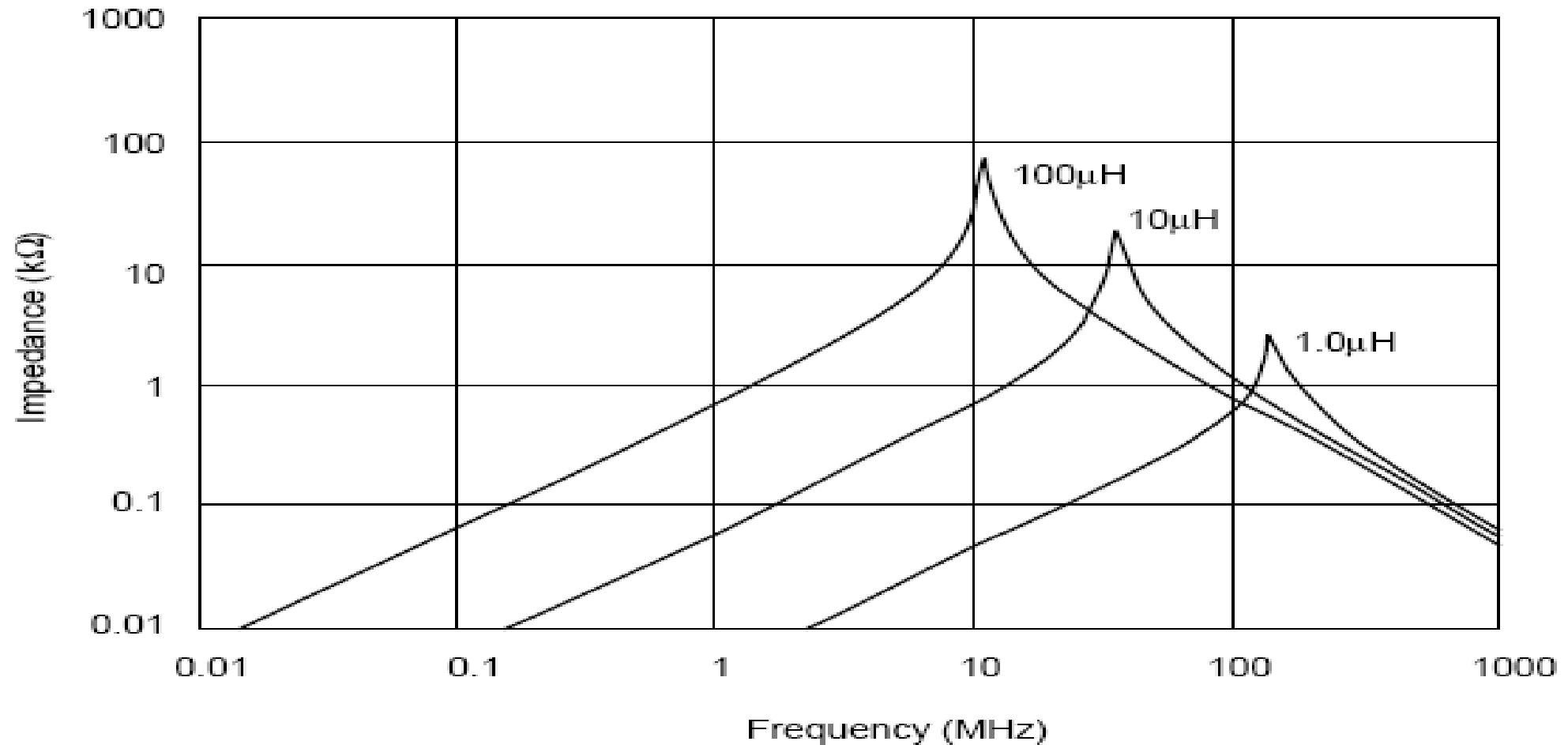
- At extremely low frequency,
 - ❖ the inductor usually behaves like a resistor, and
 - ❖ as the frequency becomes higher, the reactance due to the inductance arising from the winding also becomes dominant and
 - ❖ then it behaves as an inductor.

Impedance Characteristic of a Chip-type Inductor

- As the frequency becomes much higher,
 - ❖ the impedance of the capacitor connected in parallel becomes smaller and then
 - ❖ the inductor behaves as a capacitor.
 - ❖ Thus the approximate frequency range for using an inductor is usually:

$$\frac{R}{L} < \omega < \frac{1}{\sqrt{LC}}$$

Impedance characteristics with frequency of a chip inductor (Murata LQH31C)



Impedance Characteristic of a Chip-type Inductor

- In this figure, examining the 100 μH curve,
- ❖ it is found that, the impedance increases linearly with frequency up to 10 MHz.
 - ❖ Thus below 10 MHz its behavior as an inductor can be verified.
 - ❖ Since the impedance value at 1 MHz appears to be approximately 1k ohm, the inductance is found to be:

$$L = \frac{X_L}{2\pi f} \cong \frac{1 \times 10^3}{2\pi \times 1 \times 10^6} = \frac{1}{2\pi} \text{ mH} = 159 \mu\text{H}$$

Impedance Characteristic of a Chip-type Inductor

- As the frequency increases,
 - ❖ the impedance begins to fall after reaching a maximum point;
 - ❖ which is due to the influence of the capacitor in the equivalent circuit
 - ❖ thus, as the frequency becomes much higher, the inductor acts as a capacitor.
- Assuming that at a frequency of 100 MHz it is mainly a capacitor; then

$$C = \frac{1}{2\pi fX_C} \cong \frac{1}{2\pi \times 1 \times 10^3 \times 100 \times 10^6} = \frac{10}{2\pi} \text{ pF} \cong 1.59 \text{ pF}$$

Impedance Characteristic of a Chip-type Inductor

□ Furthermore, since the resistance is 100 kohm at the maximum point in Fig. 2.11, then the value of the series resistor in the equivalent circuit becomes: $[Z_{eq} = QX_L, Q = X_L/R]$

Thus

$$\frac{(\omega_o L)^2}{R} = 100 \text{ K}$$

and from this a value of

$$R = \frac{(\omega_o L)^2}{100 \text{ K}} = \frac{(2\pi \times 10 \times 10^6 \times 100 \times 10^{-6})^2}{100 \times 10^3} = 4\pi^2 \times 10 \cong 390\Omega$$

is obtained.

Chip-Type Resistor

- ❑ Chip-type resistor is manufactured by
 - ❖ printing a resistive material (RuO_2) on a ceramic substrate and after the conductor pattern has been printed (Thick-film electrode),
 - ❖ terminals are plated to make it possible for soldering.
- ❑ In order to prevent oxidation or damage to the resistive material;
 - ❖ a glassy material is coated on the resistive material in a postprocessing.
- ❑ A similar specification to that of capacitors (1005, 1608, and 2010) is used in the identification of chip resistors too.

Chip-Type Resistor...

□ Depending on the manufacturer,

❖ the value of the resistor is marked on its surface which makes the identification of the value of the resistor much easier.

□ Following a general notation,

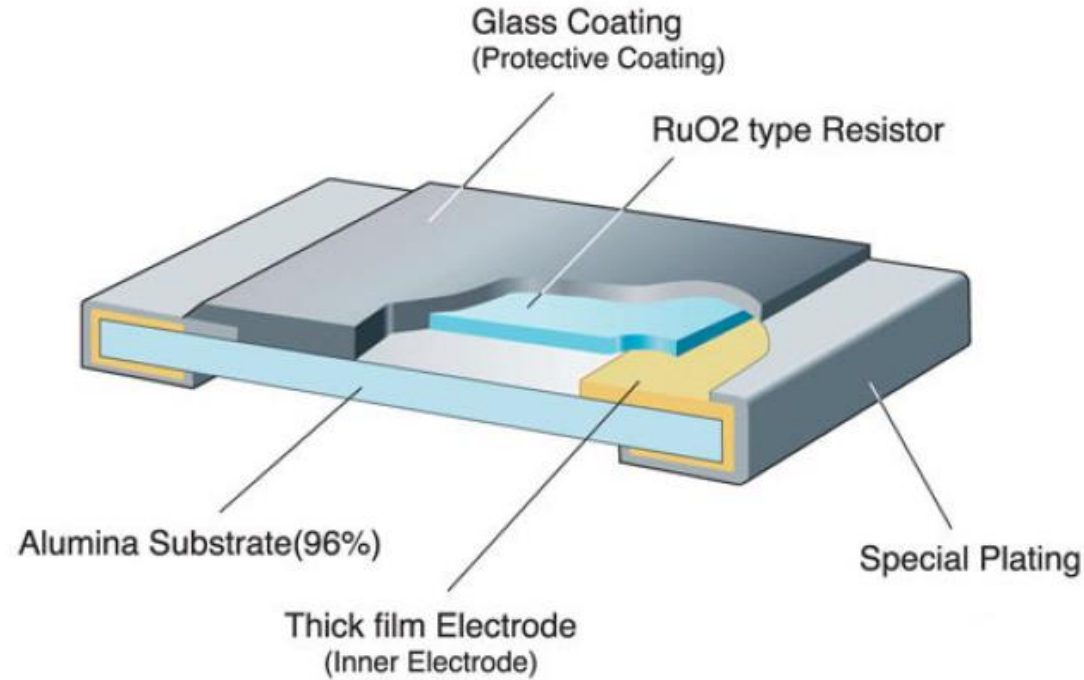
❖ the first two digits represent the effective value of the resistance and

❖ the remaining digits represent the exponent;

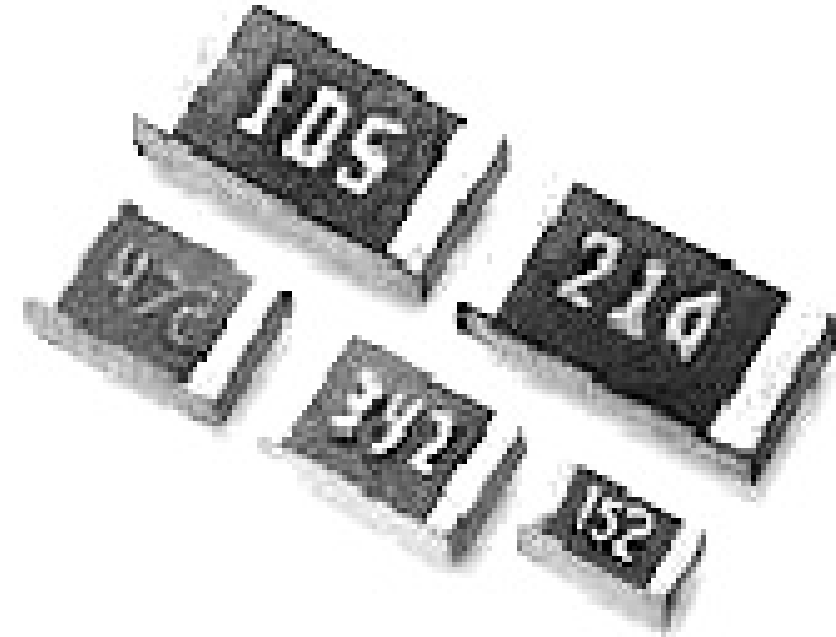
❖ thus a 3.4k resistor is denoted as:

$$342 = 34 \times 10^2 = 3.4 \times 10^3 = 3.4 \text{ k}\Omega$$

Diagram of a Chip-type Resistor



(a) structure



(b) photo

Frequency Characteristics and Equivalent Circuit of a Chip Resistor

- ❑ The frequency characteristics and equivalent circuit of a chip resistor is generally not known.
- ❑ This may be determined from impedance measurement
 - ❖ from which the equivalent circuit and impedance characteristics can be known.
- ❑ However, similar to a capacitor,
 - ❖ the impedance characteristics of chip resistors generally becomes more ideal as the size gets smaller.

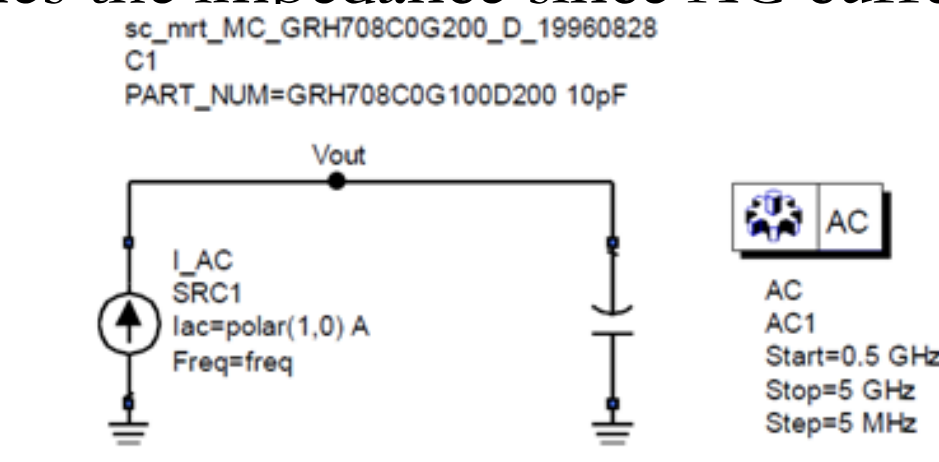
Equivalent Circuit of Capacitor by Simulation

□ Example

- ❖ Open the Murata capacitor library in ADS and after measuring the 10 pF impedance by simulation; obtain its equivalent circuit

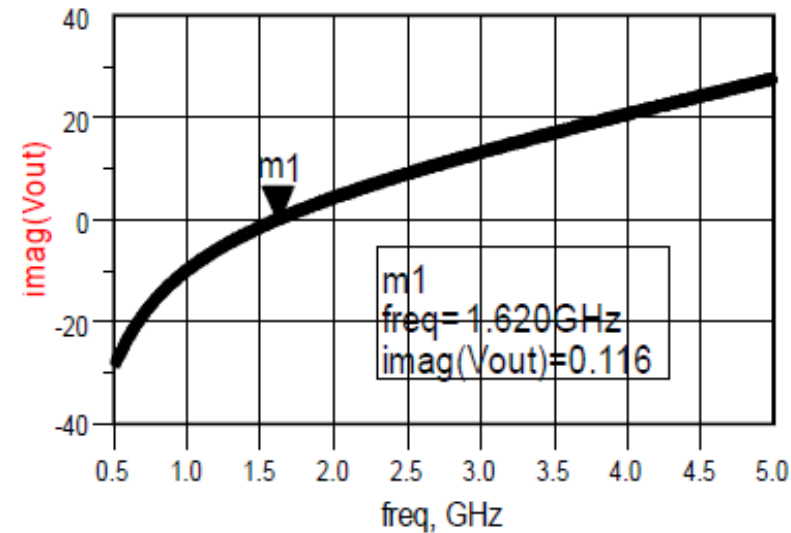
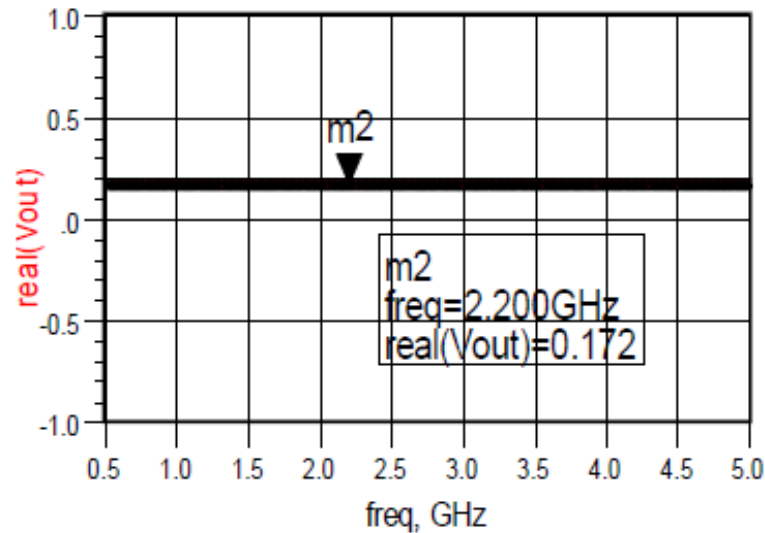
□ Solution

- ❖ In the schematic, **Vout** becomes the impedance since AC current source is set to 1A.



Equivalent Circuit of Capacitor by Simulation

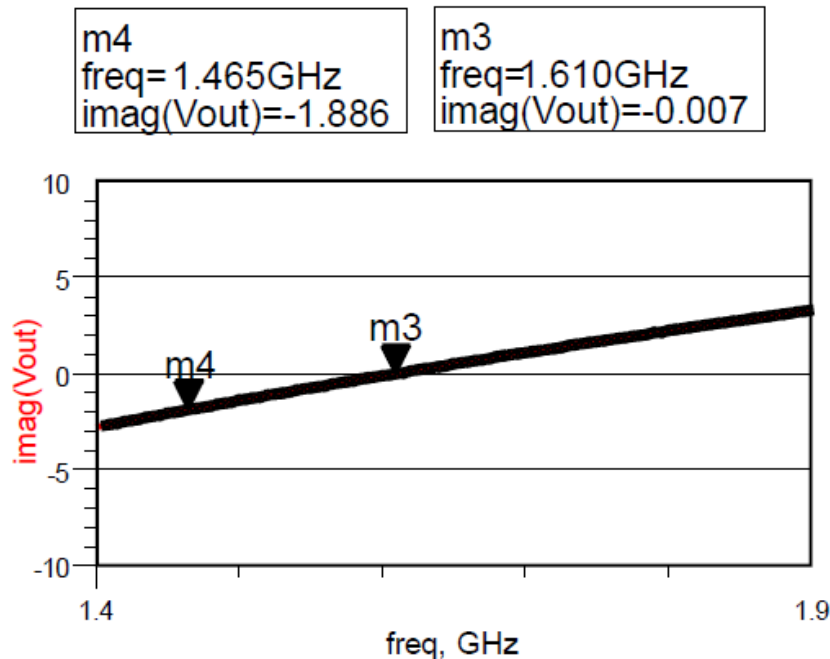
- Plotting the real and imaginary parts of V_{out} separately,
- the value of the real part is read as $R = 0.17 \Omega$.



Equivalent Circuit of Capacitor by Simulation

□ the slope near the resonant frequency becomes

$$\left. \frac{\partial X}{\partial f} \right|_{f_0} = 2\pi \left. \frac{\partial X}{\partial \omega} \right|_{f_0} = 2\pi \left. \frac{\partial}{\partial \omega} \left(\omega L - \frac{1}{\omega C} \right) \right|_{f_0} = 4\pi L$$



Eqn $L = (m3 - m4) / (\text{indep}(m3) - \text{indep}(m4)) / (4 * \pi)$
 Eqn $C = 1 / ((2 * \pi * \text{indep}(m3)) ** 2 * L)$
 Eqn $X = 2 * \pi * \text{freq} * L - 1 / (2 * \pi * \text{freq} * C)$

freq	C	L
500.0 MHz	6.763E-12	1.037E-9
505.0 MHz	6.763E-12	1.037E-9
510.0 MHz	6.763E-12	1.037E-9
515.0 MHz	6.763E-12	1.037E-9
520.0 MHz	6.763E-12	1.037E-9
525.0 MHz	6.763E-12	1.037E-9
530.0 MHz	6.763E-12	1.037E-9

Equivalent Circuit of Capacitor by Simulation

□ Comparison

